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Program

THERMINIC Live Day 23.9.2021

- 9:00 – 9:10 WELCOME ON BEHALF OF THE ORGANISING COMMITTEE AND IEEE**
- 9:10 – 10:00 KEYNOTE**
Chair: Bernhard Wunderle, TU Chemnitz
The Challenge of Thermal and Mechanical Design of Power Electronics for BEV (Battery Electric Vehicles).....N/A
Dr. Markus Klingler – Robert Bosch GmbH
- ((Ⓜ)) 10:00 – 10:45 SESSION 1: THERMAL CHARACTERISATION I**
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LUNCH

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HONOURING THE MEMORY OF PROF. VLADIMIR SZEKELY

Marta Rencz, Budapest University of Technology & Economics

(☎)

2:00 – 2:45

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Session Chair: Mohamad Abo Ras, Berliner Nanotest und Design GmbH

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Chair: Mohamad Abo Ras, Berliner Nanotest und Design GmbH

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Chair: Ralph Schacht, Brandenburgische Technische Universität Cottbus-Senftenberg

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- 5:55 – 6:00 **AC: AWARD CEREMONY**
Chair: John Janssen, NXP Semiconductors
- 6:00 – 6:10 **CLOSING OF CONFERENCE**
Chair: Bernhard Wunderle, TU Chemnitz